

Status of TPC R&D@Japanese group

LP0: small prototype MPTPC

LP1: realistic shape + realistic electronics
(non-compact type)

future

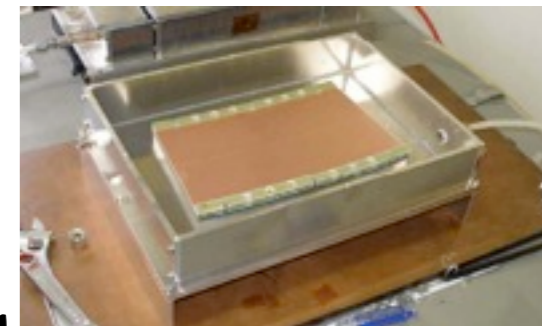
LP1.5 : realistic shape + compact electronics
sAltro16

(+ Gate ?)

LP2? : more realistic ??

History of asian module

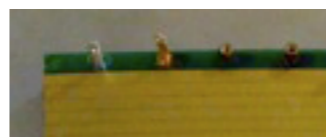
PrePrototype before LP1 start
trial board studied HV routing
mechanical stretch by screw against metal post



LP1 asian module
follow the preprototype,
PCB made by Tsinghua U.
fabrication: flatness

HV connection :

stretch : metal post

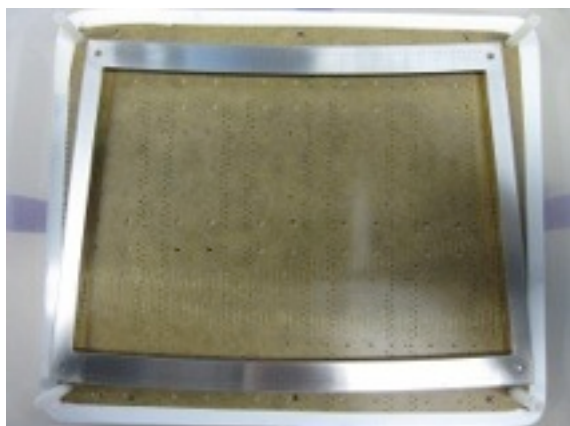
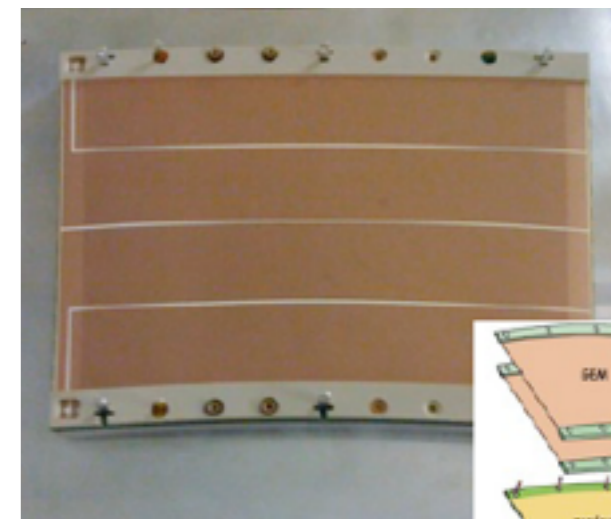
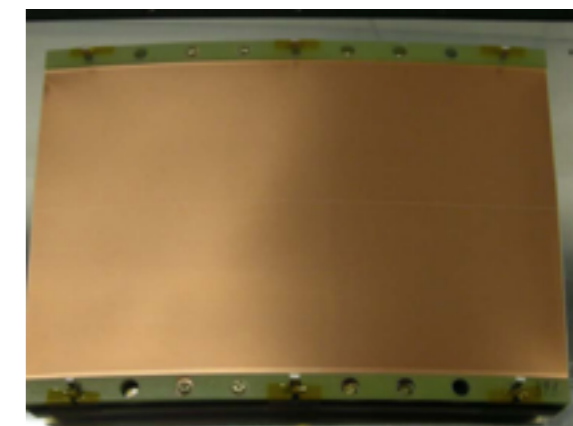


GEM segmentation
distortion at gap

GEM trip

no segmentation of the top GEM (on going)
(put holes on side)

prepare wire gate (non alternative electrode)
no time to take data w/ this @2012 beamtest



distortions from module gap@ LP1

